

Peter W. Deutsch

Cambridge – Massachusetts

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Education

Massachusetts Institute of Technology

PhD Student, Electrical Engineering and Computer Science

2022 – Present

Doctoral Supervisor: Prof. Mengjia Yan

Massachusetts Institute of Technology

Master of Science, Electrical Engineering and Computer Science

2020 – 2022

Thesis: Mitigating Memory Controller Side-Channels

Masters Supervisor: Prof. Mengjia Yan

University of British Columbia

Bachelor of Applied Science, Computer Engineering

2014 – 2020

Undergraduate Supervisors: Prof. Mieszko Lis & Prof. Prashant Nair

Publications

Peter W. Deutsch, Harish D. Dixit, Gautham Vunnam, Carl Moran, Eleanor Ozer, and Sriram Sankar. PinDrop: Breaking the silence on SDCs in a large-scale fleet. In *Proceedings of the 32nd IEEE International Symposium on High-Performance Computer Architecture (HPCA)*, 2026.

Peter W. Deutsch*, Vincent Quentin Ulitzsch*, Sudhanva Gurumurthi, Vilas Sridharan, Joel Emer, and Mengjia Yan. DelayAVF: Calculating architectural vulnerability factors for delay faults. In *Proceedings of the 57th IEEE/ACM International Symposium on Microarchitecture (MICRO)*, 2024.

Peter W. Deutsch, Weon Taek Na, Thomas Bourgeat, Joel S Emer, and Mengjia Yan. Metior: A comprehensive model to evaluate obfuscating side-channel defense schemes. In *Proceedings of the 50th Annual International Symposium on Computer Architecture (ISCA)*, pages 1–16, 2023.

Peter W. Deutsch*, Yuheng Yang*, Thomas Bourgeat, Jules Drean, Joel S Emer, and Mengjia Yan. DAGguise: Mitigating memory controller side-channels. In *Proceedings of the 27th ACM International Conference on Architectural Support for Programming Languages and Operating Systems (ASPLOS)*, pages 329–343, 2022.

Oliver Willers, Christopher Huth, Jorge Guajardo, Helmut Seidel, and Peter Deutsch. On the feasibility of deriving cryptographic keys from MEMS sensors. *Journal of Cryptographic Engineering*, 10(1):67–83, 2020.

Invited Talks

Machine Learning Accelerator Reliability: Assessing Faults During Training
Advanced Micro Devices (AMD) - Architecting for Marginal Defects Working Group

May 2025

DelayAVF: Calculating Architectural Vulnerability Factors for Delay Faults
Advanced Micro Devices (AMD) - Architecting for Marginal Defects Working Group

May 2024

Increasing Architectural Resilience to Small Delay Faults <i>MIT AI Hardware Program Symposium</i>	May 2024
Strengthening Hardware Security in the Age of AI <i>MIT CSAIL/UK GHQ Delegation</i>	Sept. 2023
Modelling Obfuscating Side-Channel Defense Schemes <i>Carnegie Mellon University - Special Topics in Hardware Security (17-715)</i>	Sept. 2023

Academic Service

IEEE Transactions on Computers <i>Reviewer</i>	2026
IEEE International Symposium on High-Performance Computer Architecture (HPCA) <i>External Review Committee Member</i>	2025
IEEE Transactions on Computers – Special Issue on Hardware Security <i>Reviewer</i>	2022

Work Experience

Research & Academic
Meta <i>PhD Intern</i>	Sunnyvale, CA 2025
<ul style="list-style-type: none"> Analyzed long-term silent data corruption (SDC) behaviours across Meta's CPU fleet. Developed reliability forecasting models for hyper-scale computing platforms, helping to scale up next-generation LLM training. 	
Advanced Micro Devices (AMD) <i>PhD Intern</i>	Austin, TX 2024
<ul style="list-style-type: none"> Applied my prior research (DelayAVF) to assess the potential reliability impacts of small delay faults in next-generation AMD products. Substantially expanded upon the existing open-source DelayAVF infrastructure to facilitate the reliability assessment of large out-of-order CPUs. 	
Massachusetts Institute of Technology <i>Teaching Assistant/Lab Assignment Developer</i>	Cambridge, MA 2022 – 2024
<ul style="list-style-type: none"> Assisted in the development and deployment of lab assignments for MIT's Secure Hardware Design course. Developed an assignment which guides students through performing and characterizing Rowhammer attacks on commodity hardware. 	
University of British Columbia <i>Undergraduate Research Student</i>	Vancouver, Canada 2019 – 2020
<ul style="list-style-type: none"> Investigated methods to detect and mitigate speculative execution attacks which utilize cache and DRAM side-channels (ex. Spectre/Meltdown). Replicated attacks, benchmarked prior work, and explored new mitigations using SPEC CPU 2017 and gem5. 	

Bosch Corporate Research	Stuttgart, Germany
<i>Microsystems Engineering Student</i>	<i>2017</i>
<ul style="list-style-type: none"> • Researched the use of MEMS gyroscopes as Physical Unclonable Functions (PUFs), facilitating reliable secret key generation in IoT devices. • Helped to devise and evaluate entropy extraction schemes to generate cryptographically secure keys from highly correlated device features. 	
University of British Columbia	Vancouver, Canada
<i>Undergraduate Teaching Assistant</i>	<i>2016 – 2020</i>
<ul style="list-style-type: none"> • Conveyed Verilog-focused digital design content to hundreds of second and third-year undergraduate students. • Taught CPEN 211 (Introduction to Microcomputers), CPEN 311 (Digital Systems Design), and CPEN 391 (Computer Engineering Design Studio II). 	
Industry	
Intel Corporation	Vancouver, Canada
<i>Verification Engineer Intern</i>	<i>2018 – 2019</i>
<ul style="list-style-type: none"> • Verified system controller ASICs for Intel NAND devices using SystemVerilog and the Universal Verification Methodology (UVM). • Designed end-to-end traffic tests to confirm compliance to internal architecture requirements and flash interface specifications, ensuring that comprehensive code coverage was achieved. 	
Microsemi (Microchip)	Vancouver, Canada
<i>Product Design Engineer Intern</i>	<i>2017</i>
<ul style="list-style-type: none"> • Designed and verified top-level RTL glue logic (SystemVerilog & VHDL) for SAS/SATA RAID controllers. • Implemented appropriate pipelining and clock-domain-crossing synchronization strategies, ensuring that timing closure and MTBF thresholds were met. 	
Awards	
Graduate	
HPCA Best Paper Candidate (PinDrop)	2026
<i>Awarded to the best 4 (out of 119) papers accepted to HPCA in 2026</i>	
IEEE Micro Top Picks Honourable Mention (DelayAVF)	2025
<i>Awarded to papers deemed the most significant in computer architecture research in 2024</i>	
Google Research Scholar Grant	2023
<i>Topic: Leveraging Accessible Signals for the Efficient Discovery of Corrupt Execution Errors</i>	
Advanced Television and Signal Processing Fellowship	2020
<i>Awarded on the recommendation of the Department Head of EECS</i>	
Undergraduate	
Dean's Prize for Academic Excellence in Engineering	2020
<i>Awarded to the head of the graduating undergraduate class in Applied Science</i>	
ECE Capstone Faculty Award	2020
<i>Presented to the top ECE Capstone (final year) project teams in 2020</i>	
NSERC Undergraduate Student Research Award	2019
<i>Awarded on the recommendation of the Faculty of Applied Science</i>	

Trek Excellence Scholarship for Continuing Students	2015, 2016, 2017, 2019
<i>Awarded to students in the top 5% of their program</i>	
PMC-Sierra Founders Award in Electrical and Computer Engineering	2019
<i>Awarded on the recommendation of the Department Head of Computer Engineering</i>	
Elizabeth and Leslie Gould Scholarship in Engineering	2019
<i>Awarded on the recommendation of the Faculty of Applied Science</i>	
J Fred Muir Memorial Scholarship in Engineering	2017
<i>Awarded on the recommendation of the Faculty of Applied Science</i>	
J K Zee Memorial Scholarship	2016
<i>Awarded on the recommendation of the Faculty of Applied Science</i>	

Volunteerism

MIT Graduate Application Assistance Program	Cambridge, MA
<i>Treasurer/Graduate Student Volunteer</i>	<i>2021 – Present</i>
• Worked with underrepresented MIT PhD applicants, providing advice and detailed feedback on personal and research statements.	
• Coordinated finances for the program, raising funds to provide fee waivers for underprivileged applicants.	
BC COVID-19 3D Printing Group (BCC3D)	Vancouver, Canada
<i>Printing / Distribution Volunteer</i>	<i>2020</i>
• Personally manufactured 300+ 3D printed face shield visors and 'ear savers' for use at hospitals and clinics.	
• Inspected, sanitized, and packed 10,000+ articles of PPE produced by local volunteers.	